Contact Name Title - Contact Product Enviro Compliance Authorized Representative* Title - Representative Product Enviro Compliance Authorized Representative* Product Enviro Compliance Product Enviro Compliance NA Product Enviro Compliance NA Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards @ onsemi.com Na Product-Env-Stewards @ onsemi.com Na Na Na Na Na	PC GOCIATION CONNECTING CTRONICS INDUSTRIES®	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Co	2-21.1										ials and Mf	g Informat	ion		
Inter Name Title - Contact Product Enviro Compliance Title - Representative Title - Representative Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Effective Date Version Manufacturing Site Weight* UOM Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material Terminal Base Alloy Manufacturing Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Manufacturing Number of Reflow Cycles Manufacturing Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Manufacturing Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	pplier Informa	ation								,					
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Product-Env-Stewards@onsemi.com Requester Item Number Product Enviro Compliance NA Product-Env-Stewards@onsemi.com Na Naunfacturing Site Weight* UOM Nanufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Natte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	tact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
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vel 1 - maximum time at peak temperature during soldering is 10-30 seconds		no at nook tomporatur	o during col	doring is 10.3	20 soconds										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belie as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.1	mg	Supplier	Zinc (Zn)	7440-66-6		0.0229	mg
			Supplier	Iron (Fe)	7439-89-6		0.4489	mg
			Supplier	Copper (Cu)	7440-50-8		18.6225	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0057	mg
Die	2.54	mg	Supplier	Silicon (Si)	7440-21-3		2.54	mg
Lead Frame	46.436	mg	Supplier	Silver (Ag)	7440-22-4		0.065	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0464	mg
			Supplier	Iron (Fe)	7439-89-6		0.9752	mg
			Supplier	Copper (Cu)	7440-50-8		45.303	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0464	mg
Mold Compound-Black	42.7	mg		Proprietary	proprietary data		3.416	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2135	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.0705	mg
Plating	8.33	mg	Supplier	Tin (Sn)	7440-31-5		8.33	mg
Solder Paste	3.017	mg	Supplier	Silver (Ag)	7440-22-4		0.0754	mg
			A	Lead (Pb)	7439-92-1	7a	2.8812	mg
			Supplier	Tin (Sn)	7440-31-5		0.0603	mg
Wire Bond - Cu	0.013	mg	Supplier	Palladium (Pd)	7440-05-3		0.0002	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0128	mg